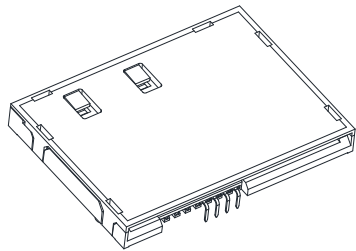




**ALTERNATIVE
COMPONENT
SOURCE**

a Major League Electronics Company

2533 Centennial Blvd. Jeffersonville, Indiana, USA 47130



EMV Compliant

TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimension: 55.50L x 40.00W x 5.80H mm
 Weight: Approx. 12.55 g
 Contact principle: Landing technology
 Operating position: Shaft up / Down / Horizontal
 Mounting System: DIP or SMT Type (with post)
 Durability: 500,000 cycles min.

2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0
 RoHS Directive 2011/65/EU Compliant

3. Electrical Characteristics

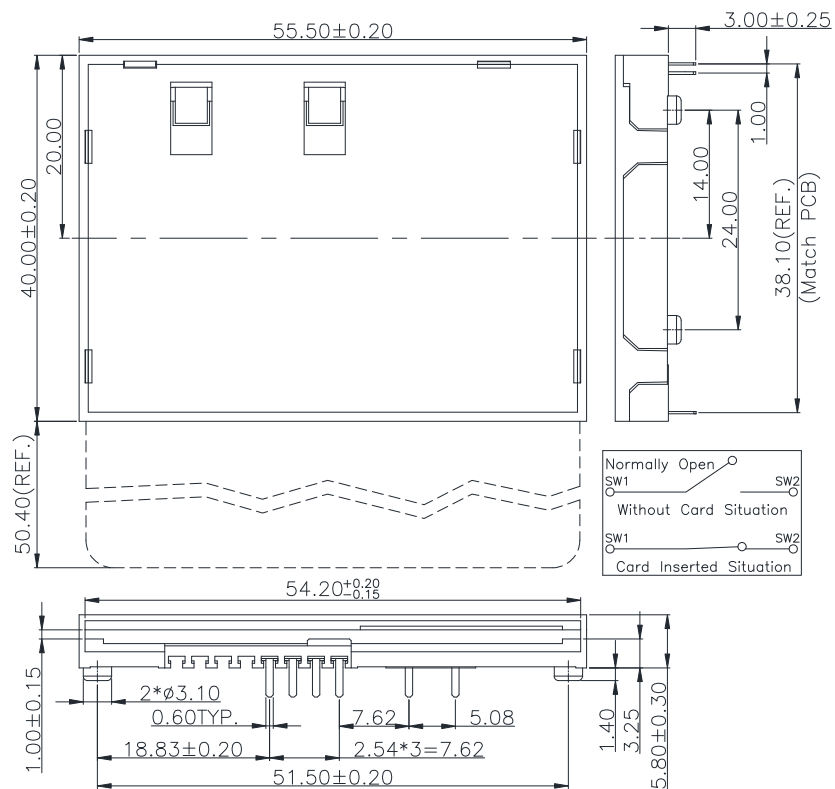
Number of contacts: 8 pins
 Contact resistance: 50 mΩ typical, 100 mΩ max.
 Insulation resistance: >1000 MΩ / 500 VDC
 Switch type: Sealed
 Operation: Normally Open

4. Solderability

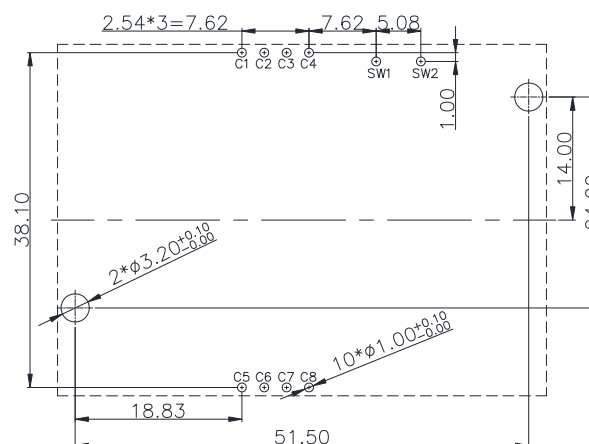
Wave: 260 C, 5 sec. Max.
 IR reflow: Not applicable
 Manual soldering: 360 C, 3 sec. Max.

5. Environmental Characteristics

Operating temperature: - 40 C ~ + 85 C
 Operating humidity: 10 % ~ 95 % RH
 Storage temperature: - 40 C ~ + 85 C
 Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: 0.15 mm
Mechanical outline dimension



Unit: mm; Tolerances: 0.05 mm
Reference dimension for PCB layout

Smart Card Acceptor

Model No.: ICA-705 DIP

Revision: 1.5

Date: MAY 01, 2014